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10/09/01

U.S. UTILITY Patent Application

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PATENT NUMBER and
ISSUE DATE

APPL NUM 10004172	FILING DATE 10/09/2001	CLASS 029	SUBCLASS 843	GAU 3726	EXAMINER Tugbary
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*APPLICANTS: Farnworth Warren; Wood Alan;

*CONTINUING DATA VERIFIED: YES NOT

THIS APPLICATION IS A DIV OF 09/148,723 09/03/1998

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* FOREIGN APPLICATIONS VERIFIED: NONE NOT

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	MI22-1830
Verified and Acknowledged Examiners's initials <u>MT</u>	
TITLE: Methods of bonding solder balls to bond pads on a substrate, and bonding frames	
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)	

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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